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- BiCMOS Design Substantially Reduces I_{CCZ}
- Output Ports Have Equivalent 25-Ω Resistors; No External Resistors Are Required
- Specifically Designed to Drive MOS DRAMs
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Flow-Through Architecture Optimizes PCB Layout
- Power-Up High-Impedance State
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic and Ceramic 300-mil DIPs (JT, NT)

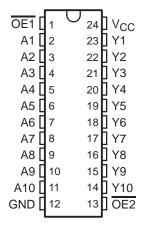
description

These 10-bit buffers and bus drivers are specifically designed to drive the capacitive input characteristics of MOS DRAMs. They provide high-performance bus interface for wide data paths or buses carrying parity.

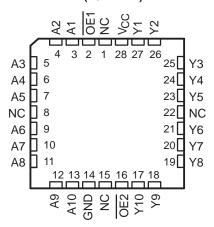
The 3-state control gate is a 2-input AND gate with active-low inputs so if either output-enable (OE1 or OE2) input is high, all ten outputs are in the high-impedance state. The outputs are also in the high-impedance state during power-up and power-down conditions. The outputs remain in the high-impedance state while the device is powered down.

The SN54BCT2827C is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74BCT2827C is characterized for operation from 0°C to 70°C.

SN54BCT2827C . . . JT OR W PACKAGE SN74BCT2827C . . . DW OR NT PACKAGE (TOP VIEW)



SN54BCT2827C . . . FK PACKAGE (TOP VIEW)



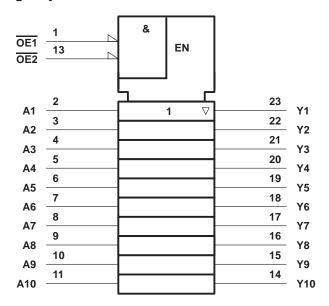
NC - No internal connection

FUNCTION TABLE

ı	NPUTS	OUTPUT			
OE1	OE2	Α	Υ		
L	L	L	L		
L	L	Н	Н		
Н	X	Χ	Z		
Χ	Н	Χ	Z		

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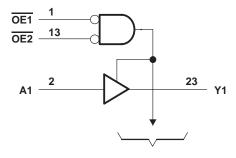
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

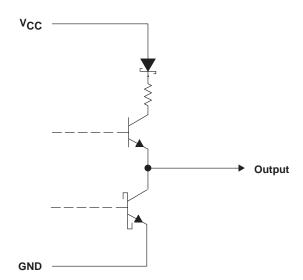
Pin numbers shown are for the DW, JT, NT, and W packages.

logic diagram (positive logic)



To Nine Other Channels

schematic of each output



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the disabled or power-off state, VO	0.5 V to 5.5 V
Voltage range applied to any output in the high state, V _O	\dots -0.5 V to V _{CC}
Input clamp current, I _{IK}	–30 mA
Current into any output in the low state	24 mA
Operating free-air temperature range: SN54BCT2827C	. −55°C to 125°C
SN74BCT2827C	0°C to 70°C
Storage temperature range	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54BCT2827C			SN7	LINUT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
lik	Input clamp current			-18			-18	mA
lOH	High-level output current			-1			-1	mA
lOL	Low-level output current			12			12	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		SN54	BCT28	27C	SN7				
PARAMETER	TEST (MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT	
VIK	$V_{CC} = 4.5 V,$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	V _{CC} -2			V _{CC} -2			V
	\\ 45\\	I _{OL} = 1 mA		0.15	0.5		0.15	0.5	V
VOL	V _{CC} = 4.5 V	$I_{OL} = 12 \text{ mA}$		0.35	0.8		0.35	0.8	V
lozh	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 V$			20			20	μΑ
lozL	V _{CC} = 5.5 V,	V _O = 0.5 V			-20			-20	μΑ
lOL(sink)	$V_{CC} = 4.5 \text{ V},$	V _O = 2 V	50			50			mA
IĮ	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA
lін	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.5 V			-0.2			-0.2	mA
ΙΟ [§]	V _C C = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
ICCL	V _{CC} = 5.5 V,	Outputs open		28	40		28	40	mA
lccz	V _{CC} = 5.5 V,	Outputs open		3.8	6		3.8	6	mA
Ci	V _C C = 5 V,	V _I = 2.5 V or 0.5 V		5			5		pF
Co	V _{CC} = 5 V,	V _I = 2.5 V or 0.5 V		8			8		pF

 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short circuit output current, los.



NOTE 1: The input negative-voltage rating may be exceeded if the input clamp current rating is observed.

SN54BCT2827C, SN74BCT2827C 10-BIT BUS/MOS MEMORY DRIVERS WITH 3-STATE OUTPUTS SCBS007E - APRIL 1987 - REVISED NOVEMBER 1993

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)		C _L R1 R2 T _A	C = 5 V, = 50 pF = 500 Ω = 500 Ω = 25°C	;),	C _L R1 R2 T _A	$= 50 \text{ pF},$ $= 500 \Omega$ $2 = 500 \Omega$ $3 = 500 \Omega$, MAX [†]		UNIT		
			′B(CT2827	<u> </u>	SN54BC	T2827C	SN74BC	T2827C			
			MIN	TYP	MAX	MIN	MAX	MIN	MAX			
t _{PLH}	^	Υ	0.9	3.6	5.2	0.9	6.6	0.9	6			
t _{PHL}	A		Ť	2	5.1	7.2	2	8.2	2	7.8	ns	
^t PZH	ŌĒ	Υ	2.8	5.6	8	2.8	10.7	2.8	10.7	20		
t _{PZL}	OE	Y	5	8.9	11	5	13.7	5	12.9	ns		
^t PHZ	ŌĒ	Υ	3.2	6.7	8.5	3.2	14	3.2	13	ne		
t _{PLZ}	OE	Ť	Y	Υ	2.7	5.3	10.5	2.7	11	2.7	10	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.





PACKAGE OPTION ADDENDUM

6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74BCT2827CDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT2827C	Samples
SN74BCT2827CDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT2827C	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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6-Feb-2020

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT2827CDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74BCT2827CDWR	SOIC	DW	24	2000	350.0	350.0	43.0	

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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